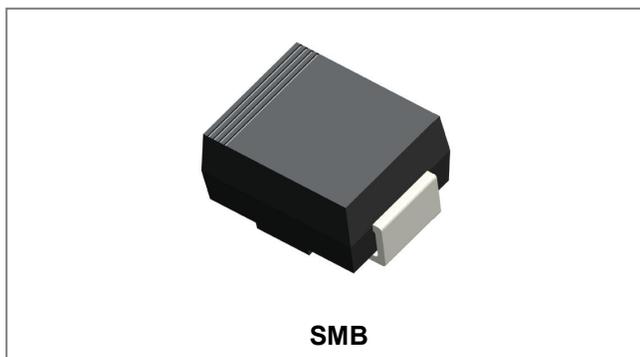


## MURS160 ULTRAFAST RECTIFIERS



### Features

- Ultra-Fast Switching
- High Current Capability
- Low Reverse Leakage Current
- High Surge Current Capability
- Plastic Material has UL Flammability Classification 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram



### Mechanical Data

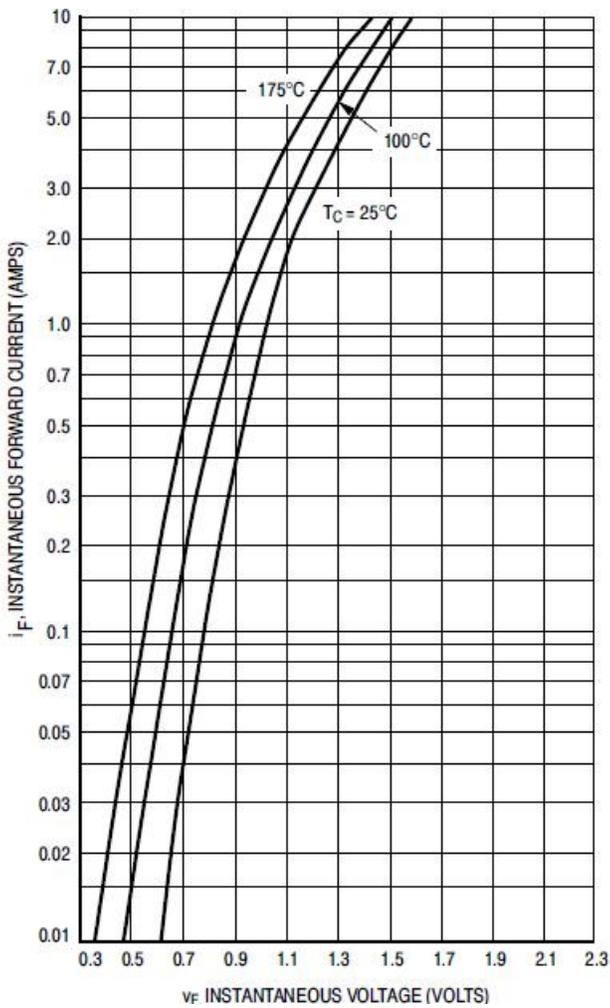
- Case: Low Profile Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.09grams(approx)

### Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

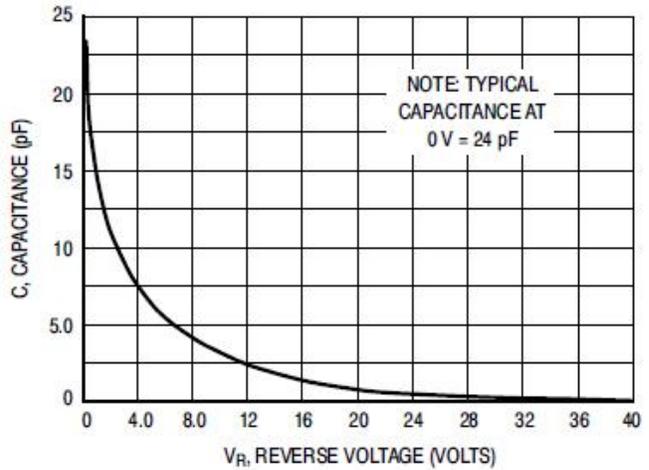
Characteristic	Symbol	MURS160	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	600	V
Average Rectified Output Current @ $T_L = 75^{\circ}\text{C}$	$I_o$	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	35	A
Forward Voltage @ $I_F = 1.0\text{A}$ , $T_J = 25^{\circ}\text{C}$	$V_{FM1}$	1.26	V
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$	$I_{RM}$	5.0 150	$\mu\text{A}$
Typical Thermal Resistance Junction to Ambient (Note 1)	$R_{\theta JA}$	80	K/W
Maximum Reverse Recovery Time (Note 2)	$T_{rr}$	50	ns
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^{\circ}\text{C}$

Note: 1. Mounted on P.C. Board with 14mm<sup>2</sup> (0.13mm thick) copper pad.  
 2. Measured with  $I_F=0.5\text{A}$ ;  $I_R=1.0\text{A}$ ;  $I_{RR}=0.25\text{A}$ .

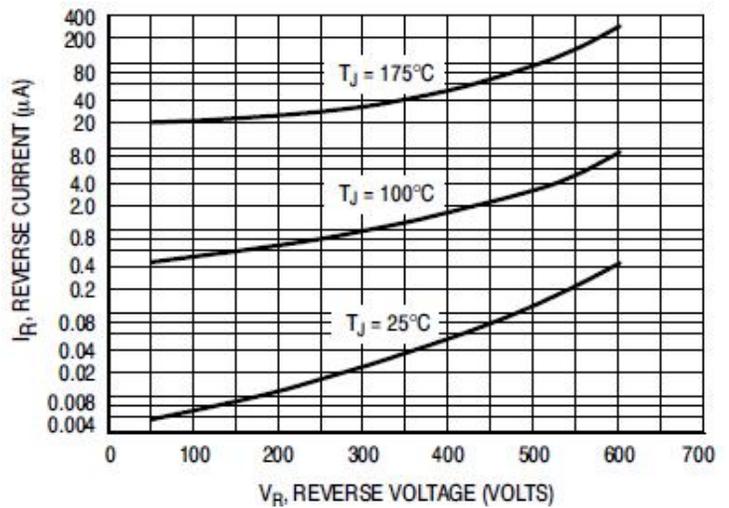
**Ratings and Characteristics Curves**



**Figure 1. Typical Forward Voltage**

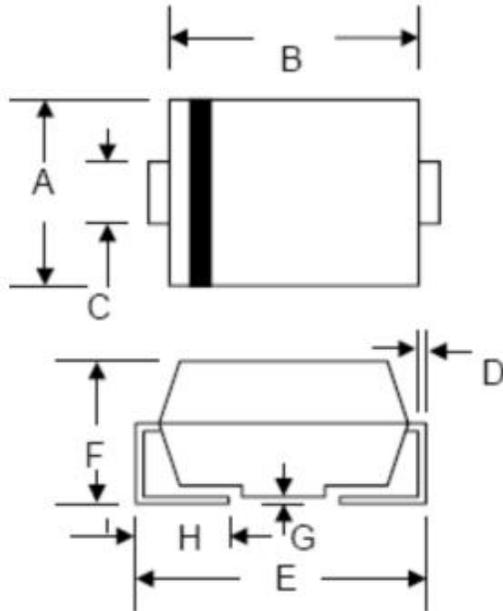


**Figure2. Typical Capacitance**



**Figure 3. Typical Reverse Current**

**Mechanical Dimensions SMB**



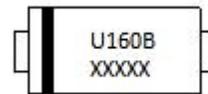
SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	3.94	0.130	0.155
B	4.06	4.70	0.160	0.185
C	1.80	2.20	0.071	0.087
D	0.152	0.305	0.006	0.012
E	4.80	5.59	0.189	0.220
F	2.10	2.60	0.083	0.102
G	0.051	0.203	0.002	0.008
H	0.76	1.52	0.030	0.060

**Ordering Information**

Device	Package	Shipping
MURS160	SMB (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**

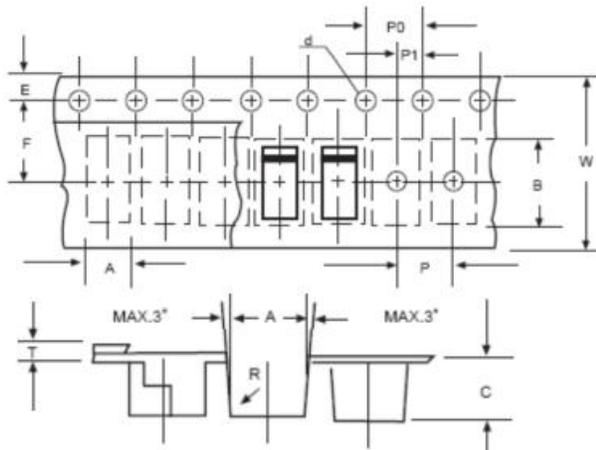


Where XXXXX is YYWWL

- U = Device Type
- 1 = Forward Current (1A)
- 60 = Reverse Voltage (600V)
- B = Package type
- YY = Year
- WW = Week
- L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Carrier Tape Specification SMB**



SYMBOL	Millimeters	
	Min.	Max.
A	2.97	3.17
B	5.70	5.90
C	2.32	2.52
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
T	0.25	0.35
W	11.80	12.20

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